

## T-1 (3mm) TRI-LEVEL LED INDICATOR

Part Number: L-934SA/1G1Y1ID

Green Yellow

High Efficiency Red

#### **Features**

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

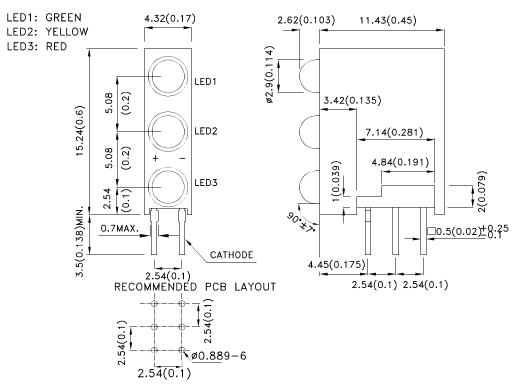
## Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

# **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
   The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAB7427 **REV NO: V.5A DATE: JUN/28/2013 PAGE: 1 OF 7** APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Q.M.Chen ERP: 1102013870





## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-934SA/1G1Y1ID	Green (GaP)	Cross Diffused	10	25	40°
		Green Diffused	*10	*25	
	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	40°
		Yellow Dillused	*8	*15	
	High Efficiency Red (GaAsP/GaP)	Ded Diffused	12	30	40°
		Red Diffused	*10	*20	

- Notes: 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

  \* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green Yellow High Efficiency Red	565 590 627		nm	IF=20mA
λD [1]	Dominant Wavelength	Green Yellow High Efficiency Red	568 588 617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green Yellow High Efficiency Red	30 35 45		nm	IF=20mA
С	Capacitance	Green Yellow High Efficiency Red	15 20 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green Yellow High Efficiency Red	2.2 2.1 2	2.5 2.5 2.5	V	IF=20mA
lr	Reverse Current	Green Yellow High Efficiency Red		10 10 10	uA	V <sub>R</sub> =5V

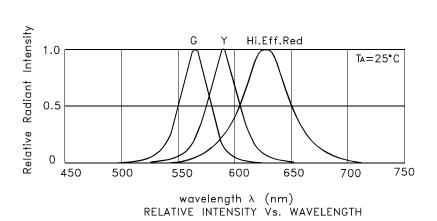
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

# Absolute Maximum Ratings at TA=25°C

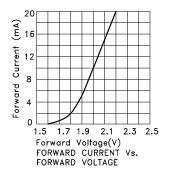
Parameter	Green	Yellow	High Efficiency Red	Units		
Power dissipation	62.5	75	75	mW		
DC Forward Current	25	30	30	mA		
Peak Forward Current [1]	140	140	160	mA		
Reverse Voltage	5					
Operating/Storage Temperature	-40°C To +85°C					
Lead Solder Temperature [2]	260°C For 3 Seconds					
Lead Solder Temperature [3]	260°C For 5 Seconds					

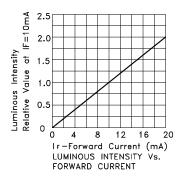
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
  2. 2mm below package base.
  3. 5mm below package base.

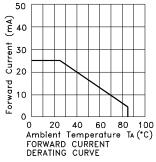
SPEC NO: DSAB7427 **REV NO: V.5A DATE: JUN/28/2013** PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Q.M.Chen ERP: 1102013870

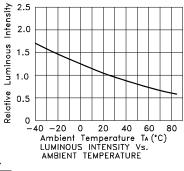


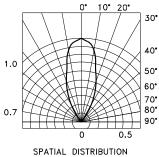
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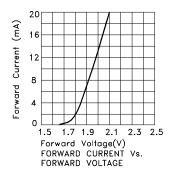


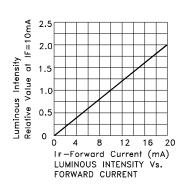


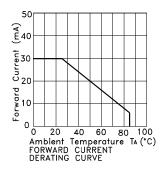
 SPEC NO: DSAB7427
 REV NO: V.5A
 DATE: JUN/28/2013
 PAGE: 3 OF 7

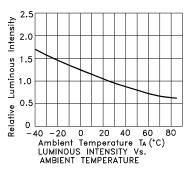
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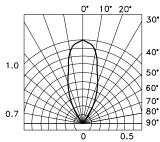
## Yellow









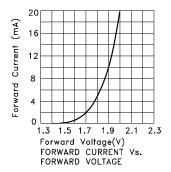


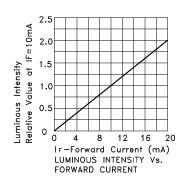
SPATIAL DISTRIBUTION

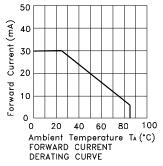
SPEC NO: DSAB7427 REV NO: V.5A DATE: JUN/28/2013 PAGE: 4 OF 7

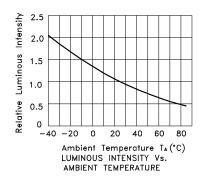
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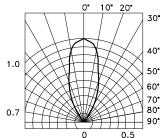
# **High Efficiency Red**











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 SPEC NO: DSAB7427
 REV NO: V.5A
 DATE: JUN/28/2013
 PAGE: 5 OF 7

 APPROVED: WYNEC
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# PACKING & LABEL SPECIFICATIONS L-934SA/1G1Y1ID 125PCS / IC TUBE OUTSIDE LABEL



750PCS / 6PCS IC TUBE

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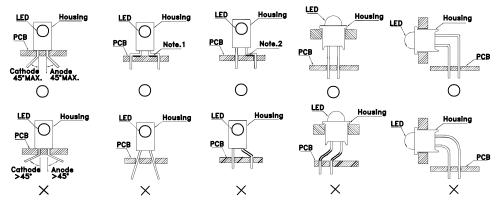
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 SPEC NO: DSAB7427
 REV NO: V.5A
 DATE: JUN/28/2013
 PAGE: 6 OF 7

 APPROVED: WYNEC
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#### **PRECAUTIONS**

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

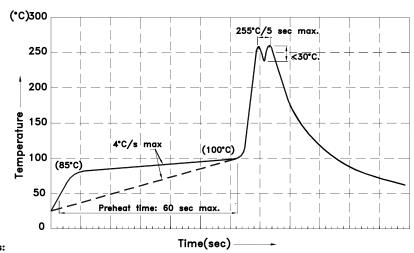


" $\bigcirc$ " Correct mounting method " $\times$ " Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C  $\sim$  255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

 SPEC NO: DSAB7427
 REV NO: V.5A
 DATE: JUN/28/2013
 PAGE: 7 OF 7

 APPROVED: WYNEC
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